SCLS587B – JUNE 2004 – SEPTEMBER 2004

 Qualification in Accordance With AEC-Q100[†] 	D OR PW PACKAGE (TOP VIEW)
 Qualified for Automotive Applications 	
 Customer-Specific Configuration Control Can Be Supported Along With Major-Change Approval 	1A [1 14] V _{CC} 1B [2 13] 4B 1Y [3 12] 4A 2A [4 11] 4Y
 Wide Operating Voltage Range of 2 V to 6 V 	
 Outputs Can Drive Up To 10 LSTTL Loads 	2Y [] 6 9 [] 3A
 Low Power Consumption, 20-μA Max I_{CC} 	GND [] 7 8]] 3Y
• ±4-mA Output Drive at 5 V	
 Low Input Current of 1 μA Max 	

True Logic

[†] Contact factory for details. Q100 qualification data available on request.

description/ordering information

This device contains four independent 2-input exclusive-OR gates. They perform the Boolean function $Y = A \oplus B$ or $Y = \overline{AB} + A\overline{B}$ in positive logic.

A common application is as a true/complement element. If one of the inputs is low, the other input is reproduced in true form at the output. If one of the inputs is high, the signal on the other input is reproduced inverted at the output.

TA	PACKAGE [‡]		ORDERABLE PART NUMBER	TOP-SIDE MARKING					
-40°C to 85°C	SOIC – D	Reel of 2500	SN74HC86IDRQ1	HC86I					
-40 C 10 85 C	TSSOP – PW	Reel of 2000	SN74HC86IPWRQ1	HC86I					
-40°C to 125°C	SOIC – D	Reel of 2500	SN74HC86QDRQ1	HC86Q					
-40 C 10 125 C	TSSOP – PW	Reel of 2000	SN74HC86QPWRQ1	HC86Q					

ORDERING INFORMATION

[‡] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

(each gate)							
INP	JTS	OUTPUT					
Α	В	Y					
L	L	L					
L	Н	Н					
н	L	Н					
Н	Н	L					



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

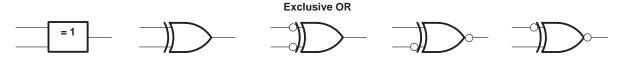


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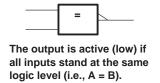
exclusive-OR logic

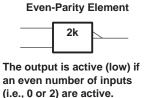
An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.



These are five equivalent exclusive-OR symbols valid for an 'HC86 gate in positive logic; negation may be shown at any two ports.

Logic Identity Element





Odd-Parity Element

The output is active (high) if an odd number of inputs (i.e., only 1 of the 2) are active.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input clamp current, I_{IK} (V _I < 0 or V _I > V _{CC}) (see Note 1)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC}) (see Note 1)	
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ _{JA} (see Note 2): D package	86°C/W
PW package	
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 3)

			MIN	NOM	MAX	UNIT
VCC	Supply voltage			5	6	V
		$V_{CC} = 2 V$	1.5			
VIH	High-level input voltage	V _{CC} = 4.5 V	3.15			V
		$V_{CC} = 6 V$	4.2			
		$V_{CC} = 2 V$			0.5	
VIL Low-leve	Low-level input voltage	V _{CC} = 4.5 V			1.35	V
		$V_{CC} = 6 V$			1.8	
VI	Input voltage		0		VCC	V
VO	Output voltage		0		VCC	V
		$V_{CC} = 2 V$			1000	
$\Delta t / \Delta v$	Input transition rise/fall time	V _{CC} = 4.5 V			500	ns
				400		
Т _А	Operating free-air temperature		-40		125	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	Vcc	T _A = −40°C TO 125°C		T _A = −40°C TO 85°C		UNIT	
			MIN	MAX	MIN	MAX		
			2 V	1.9		1.9		
		l _{OH} = -20 μA	4.5 V	4.4		4.4		
∨он	$V_{I} = V_{IH} \text{ or } V_{IL}$		6 V	5.9		5.9		V
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.7		3.84		
		I _{OH} = -5.2 mA	6 V	5.2		5.34		
			2 V		0.1		0.1	
		l _{OL} = 20 μA	4.5 V		0.1		0.1	
VOL	$V_{I} = V_{IH} \text{ or } V_{IL}$		6 V		0.1		0.1	V
		$I_{OL} = 4 \text{ mA}$	4.5 V		0.4		0.33	
		I _{OL} = 5.2 mA	6 V		0.4		0.33	
Ц	$V_{I} = V_{CC} \text{ or } 0$		6 V		±1000		±1000	nA
ICC	$V_{I} = V_{CC} \text{ or } 0,$	I ^O = 0	6 V		40		20	μΑ
Ci			2 V to 6 V		10		10	pF



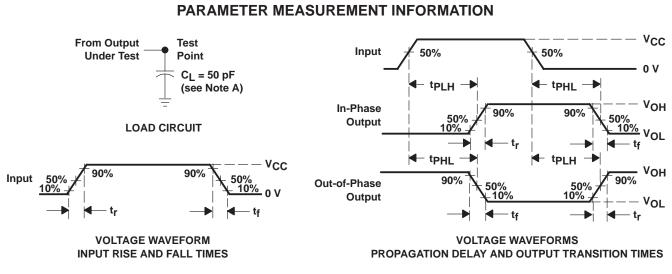
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switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM			T _A = −40°C TO 125°C	T _A = -40°C TO 85°C	UNIT
	(INPUT)	(OUTPUT)	vcc	MIN MAX	MIN MAX	
			2 V	150	125	
^t pd	A or B	Y	4.5 V	30	25	ns
			6 V	25	21	
			2 V	110	95	
tt		Y	4.5 V	22	19	ns
			6 V	19	16	

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
Cpd	Power dissipation capacitance per gate	No load	35	pF



NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_Q = 50 Ω , t_f = 6 ns, t_f = 6 ns.
 - C. The outputs are measured one at a time, with one input transition per measurement.
 - D. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74HC86IDRQ1	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR Level-1-235C-UNLIM
SN74HC86IPWRQ1	ACTIVE	TSSOP	PW	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74HC86QDRQ1	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR Level-1-235C-UNLIM
SN74HC86QPWRQ1	ACTIVE	TSSOP	PW	14	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

E. Reference JEDEC MS-012 variation AB.



MECHANICAL DATA

MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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